



PROTON-ELECTROTEX RUSSIA

High power cycling capability
Low on-state and switching losses
Designed for traction and industrial applications

Phase Control Thyristor Chip Type TG56-1250-18

Maximum allowable mean on-state current ¹⁾				I _{TAV}		1250 A		
Repetitive peak off-state voltage				V _{DRM}		1000...1800 V		
Repetitive peak reverse voltage				V _{RRM}				
Turn-off time				t _q		160, 200, 250, 320, 400, 500 μs		
V _{DRM} , V _{RRM} , V	1000	1100	1200	1300	1400	1500	1600	1800
Voltage code	10	11	12	13	14	15	16	18
T _j , °C	-60...+125							

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Maximum allowable mean on-state current ¹⁾	A	1250 1385	$T_c=90\text{ }^{\circ}\text{C}$, Double side cooled $T_c=85\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current ¹⁾	A	1962	$T_c=90\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current ¹⁾	kA	29.0 33.0	$T_j=T_{j\max}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
			30.0 35.0	$T_j=T_{j\max}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
I^2t	Safety factor ¹⁾	$\text{A}^2\text{s}\cdot 10^3$	4200 5400	$T_j=T_{j\max}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
			3700 5000	$T_j=T_{j\max}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	1000...1800	$T_{j\min}<T_j<T_{j\max}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	1100...1900	$T_{j\min}<T_j<T_{j\max}$; 180° half-sine wave; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.6\cdot V_{DRM}$ $0.6\cdot V_{RRM}$	$T_j=T_{j\max}$; Gate open	

TRIGGERING				
I_{FGM}	Peak forward gate current	A	8	$T_j = T_{j \max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	4	$T_j = T_{j \max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	1250	$T_j = T_{j \max}$; $V_D = 0.67 \cdot V_{DRM}$; $I_{TM} = 5400$ A; Gate pulse: $I_G = 2$ A; $t_{GP} = 50$ μ s; $di_G/dt \geq 2$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	$^{\circ}$ C	-60...+50	
T_j	Operating junction temperature	$^{\circ}$ C	-60...+125	
MECHANICAL				
F	Mounting force ¹⁾	kN	24.0...28.0	
F_{cg}	Force on control gate	N	7.8	

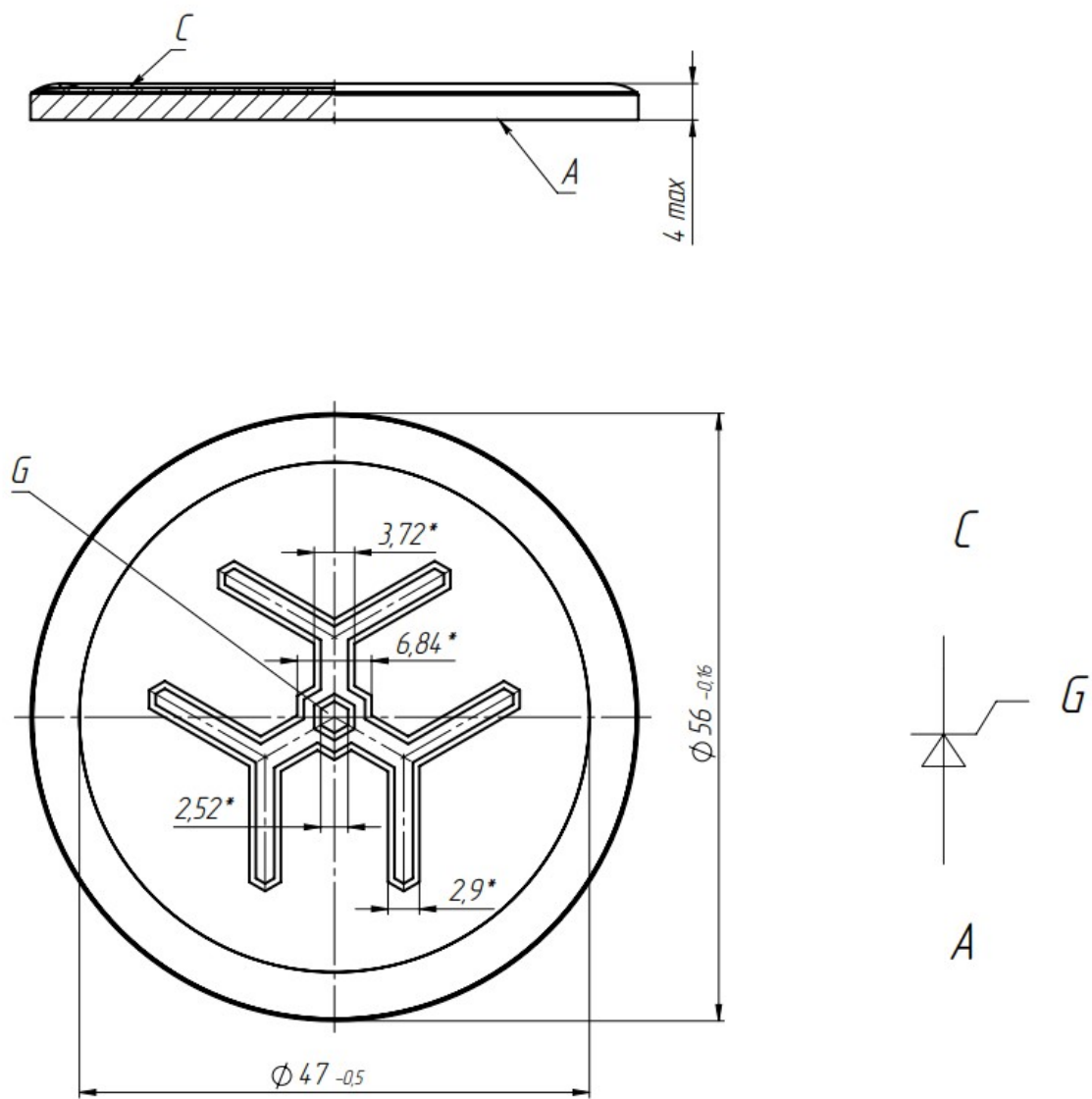
CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V _{TM}	Peak on-state voltage ¹⁾ , max	V	1.70	T _j =25 °C; I _{TM} =3925 A	
V _{T(TO)}	On-state threshold voltage, max	V	0.998	T _j =T _{j max} ;	
r _T	On-state slope resistance ¹⁾ , max	mΩ	0.179	0.5 π I _{TAV} < I _T < 1.5 π I _{TAV}	
I _L	Latching current, max	mA	1500	T _j =25 °C; V _D =12 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs	
I _H	Holding current, max	mA	300	T _j =25 °C; V _D =12 V; Gate open	
BLOCKING					
I _{DRM} , I _{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	150	T _j =T _{j max} ; V _D =V _{DRM} ; V _R =V _{RRM}	
(dv _D /dt) _{crit}	Critical rate of rise of off-state voltage ²⁾ , min	V/μs	200, 320, 500, 1000, 1600, 2000, 2500	T _j =T _{j max} ; V _D =0.67·V _{DRM} ; Gate open	
TRIGGERING					
V _{GT}	Gate trigger direct voltage, max	V	3.00 2.50 1.50	T _j = T _{j min} T _j =25 °C T _j = T _{j max}	V _D =12 V; I _D =3 A; Direct gate current
I _{GT}	Gate trigger direct current, max	mA	500 300 150	T _j = T _{j min} T _j = 25 °C T _j = T _{j max}	
V _{GD}	Gate non-trigger direct voltage, min	V	0.40	T _j =T _{j max} ; V _D =0.67·V _{DRM} ;	
I _{GD}	Gate non-trigger direct current, min	mA	55.00	Direct gate current	
SWITCHING					
t _{gd}	Delay time, max	μs	1.10	T _j =25 °C; V _D =1000 V; I _{TM} =I _{TAV} ; di/dt=200 A/μs;	
t _{gt}	Turn-on time, max	μs	3.00	Gate pulse: I _G =2 A; V _G =20 V; t _{GP} =50 μs; di _G /dt=2 A/μs	
t _q	Turn-off time ³⁾ , max	μs	160, 200, 250, 320, 400, 500	dv _D /dt=50 V/μs; T _j =T _{j max} ; I _{TM} =I _{TAV} ; di _R /dt=-10 A/μs; V _R =100V; V _D =0.67·V _{DRM}	

THERMAL					
R _{thjc}	Thermal resistance, junction to case ¹⁾ , max	°C/W	0.0180	Direct current	Double side cooled
R _{thjc-A}			0.0396		Anode side cooled
R _{thjc-K}			0.0324		Cathode side cooled
MECHANICAL					
m	Weight, max	g	500		

PART NUMBERING GUIDE						NOTES																															
TG	56	1250	18	A2	E2	1) Depending on the specifications of the housing used. The specified values are relevant when using the Proton-Electrotex T.D5 housing. 2) Critical rate of rise of off-state voltage <table><tr><td>Symbol of Group</td><td>P2</td><td>K2</td><td>E2</td><td>A2</td><td>T1</td><td>P1</td><td>M1</td></tr><tr><td>(dv_D/dt)_{crit}, V/μs</td><td>200</td><td>320</td><td>500</td><td>1000</td><td>1600</td><td>2000</td><td>2500</td></tr></table> 3) Turn-off time (dv_D/dt=50 V/μs) <table><tr><td>Symbol of Group</td><td>T2</td><td>P2</td><td>M2</td><td>K2</td><td>H2</td><td>E2</td></tr><tr><td>t_{qf}, μs</td><td>160</td><td>200</td><td>250</td><td>320</td><td>400</td><td>500</td></tr></table>		Symbol of Group	P2	K2	E2	A2	T1	P1	M1	(dv _D /dt) _{crit} , V/μs	200	320	500	1000	1600	2000	2500	Symbol of Group	T2	P2	M2	K2	H2	E2	t _{qf} , μs	160	200	250	320	400	500
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1	2	3	4	5	6																																
1. Phase Control Thyristor Chip with a distributed gate 2. Maximum diameter, mm 3. Mean on-state current, A 4. Voltage code 5. Critical rate of rise of off-state voltage, V/μs 6. Turn-off time (dv_D/dt=50 V/μs)																																					

OVERALL DIMENSIONS



**Dimensions for reference.*

All dimensions in millimeters

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